

## CLAIMS

1. A lead frame manufacturing method comprising:
  - a conveyance step of conveying, in a long-side direction at a predetermined pitch, a band-shaped lead frame with a predetermined pattern formed thereon;
  - a position determination step of detecting a distance between a predetermined portion of the lead frame and a positioning mark in a plating processing machine provided at a position adjacent to the lead frame by a first image sensor, and determining a position of the lead frame conveyed at the predetermined pitch; and
  - a plating step of forming a plating film on each region of the lead frame, the each region corresponding to the predetermined pitch.
  
2. A lead frame manufacturing method comprising:
  - a conveyance step of conveying, in a long-side direction at a predetermined pitch, a band-shaped lead frame with a predetermined pattern formed thereon;
  - a position determination step of determining, by a first image sensor, a position of the lead frame conveyed at the predetermined pitch;
  - a plating step of forming a plating film on each region of the lead frame, the each region corresponding to the predetermined pitch;
  - a detection step of detecting, by a second image sensor, a relative first position shift amount between the pattern formed on the lead frame and the plating film formed at the plating step; and
  - a correction step of correcting, based on the detected first position shift amount, the predetermined pitch such that a second position shift amount in subsequent plating decreases.

3. The lead frame manufacturing method according to claim 2, wherein  
at the detection step,  
the second image sensor simultaneously images a tail portion of a first plating film formed by a single process of the plating step and a lead portion of a second plating film formed after the first plating film.
4. The lead frame manufacturing method according to claim 2 or 3, wherein  
at the correction step, correction is made such that position shift between the pattern and the plating film is prevented or reduced across an entirety of a region where the plating film is formed by a single process of the plating step.
5. A lead frame manufacturing device comprising:  
a conveyer configured to convey, in a long-side direction at a predetermined pitch, a band-shaped lead frame with a predetermined pattern formed thereon;  
a position determinator configured to determine, by a first image sensor, a position of the lead frame conveyed at the predetermined pitch; and  
a plater configured to form a plating film on each region of the lead frame, the each region corresponding to the predetermined pitch;  
a detector configured to detect, by a second image sensor, a relative first position shift amount between the pattern formed on the lead frame and the plating film formed at the plating; and  
a corrector configured to correct, based on the detected first position shift amount, the predetermined pitch such that a second position shift amount in subsequent plating decreases.